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Global Gaming Headset Manufacturing Whitepaper 2026

Market Analysis, Supply Chain, Technology Trends & Cost
Structure

2026全球电竞耳机制造产业白皮书

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1. Executive Summary

The global gaming headset market continues its robust expansion trajectory, driven by the proliferation of esports culture, the rise of mobile gaming, and the increasing demand for immersive audio experiences. As of 2026, the global gaming headset market is estimated at approximately USD 4.8 billion, with a projected compound annual growth rate (CAGR) of 7.2% through 2030.

China remains the undisputed manufacturing hub, accounting for an estimated 78% of global gaming headset production. The Dongguan-Shenzhen corridor in Guangdong Province hosts the densest concentration of gaming peripheral manufacturers, component suppliers, mold makers, and certification laboratories anywhere in the world.

This whitepaper provides a comprehensive analysis of the global gaming headset manufacturing industry, covering market dynamics, supply chain structure, technology trends, cost breakdowns, certification requirements, and forward-looking projections. It draws on public market research data, industry association reports, and primary operational data from Dongguan Mutong Yunchuang Technology Co., Ltd. (www.dgmtyc.com), a leading gaming headset manufacturer with 8 production lines, 320+ employees, and an annual capacity of 5 million+ units.

Key Findings:

- Wireless gaming headsets (2.4GHz + Bluetooth dual-mode) are the fastest-growing segment, projected to capture 52% of market volume by 2028.
- China manufacturing cost advantage remains 25-40% over alternative locations, despite rising labor costs, due to supply chain density and automation.
- AI-powered noise cancellation and spatial audio are becoming standard features in mid-range and above products.
- The average BOM (Bill of Materials) for a mid-range 7.1 USB RGB gaming headset is USD 5.00-9.20, representing 50-65% of the factory selling price.
- Certification complexity is increasing, with the EU Battery Regulation and GPSR adding new compliance layers from 2024-2027.

2. Global Market Size & Growth

2.1 Market Overview

The global gaming headset market has evolved from a niche PC accessory category into a mainstream consumer electronics segment. Several converging factors drive this growth: the global esports audience exceeding 575 million viewers, the proliferation of gaming-capable smartphones, the rise of cloud gaming services, and the increasing importance of audio communication in multiplayer gaming.

Year	Market Size (USD B)	YoY Growth	Key Driver
2022	3.6	+8.1%	Post-pandemic gaming retention
2023	3.9	+8.3%	Wireless adoption acceleration
2024	4.2	+7.7%	Console new generation cycle
2025	4.5	+7.1%	Mobile gaming peripherals
2026 (E)	4.8	+6.7%	AI audio features
2028 (F)	5.5	+7.0% CAGR	Spatial audio standardization
2030 (F)	6.4	+7.2% CAGR	AR/VR audio integration

Source: Compiled from Grand View Research, Statista, Counterpoint Research, and industry estimates. Figures are approximate.

2.2 Regional Analysis

North America remains the largest regional market, accounting for approximately 32% of global gaming headset revenue, driven by high disposable income, a mature esports ecosystem, and strong brand loyalty. Europe follows at 26%, with Germany, the UK, and France as the core markets. The Asia-Pacific region is the fastest-growing, fueled by China's domestic market, Southeast Asia's young demographics, and India's expanding gaming population.

Region	Revenue Share	Volume Share	Growth Rate	Key Characteristics
North America	32%	24%	+5.8%	Premium segment, brand loyalty
Europe	26%	22%	+6.2%	Strict compliance, DACH focus
Asia-Pacific	28%	38%	+9.5%	Fastest growing, mobile-first
Latin America	7%	9%	+8.8%	Price-sensitive, Brazil core
Middle East & Africa	7%	7%	+10.2%	High growth, RGB preference

2.3 Segment Analysis

By Connectivity

Wired headsets still dominate in volume, particularly in esports hotel/cafe deployments and budget segments, where reliability and zero-latency are paramount. However, wireless headsets are growing at approximately 2.5x the rate of wired, driven by improved 2.4GHz low-latency technology and consumer demand for freedom of movement.

By Price Tier

The mid-range segment (USD 30-80 retail) is the largest and fastest-growing, as consumers seek a balance between features and price. The entry-level segment (under USD 30) faces intense price competition and margin pressure, while the premium segment (above USD 100) is dominated by established brands but offers the highest margins.

3. Industry Chain Analysis

3.1 Upstream Components

The gaming headset supply chain begins with core electronic and mechanical components. The key components and their supply base are concentrated in Asia, particularly in the Pearl River Delta and Yangtze River Delta regions of China.

Component	Key Suppliers	Cost Range (USD)	Supply Concentration
Acoustic Driver (40/50mm)	Multiple OEMs (CN/TW)	0.40 - 1.50	High (Pearl River Delta)
Audio DSP/USB Chip	Realtek, C-Media, Savitech	0.50 - 2.00	Very High (Taiwan/US)
Wireless SoC (2.4G/BT)	Nordic, Realtek, BES, Actions	1.00 - 3.50	High
ENC Microphone	Goertek, MEMSensing, multiple	0.20 - 0.80	Medium-High
Li-ion Battery	ATL, Desay, multiple	0.40 - 1.20	High (China)
Plastic Resin (ABS/PC)	LG Chem, Sabic, domestic	0.30 - 0.80	Global
Ear Cushion (PU/Memory Foam)	Multiple OEMs (CN)	0.50 - 1.20	Medium
Cable (Braided/USB)	Multiple OEMs (CN)	0.40 - 0.80	Medium
RGB LED + Controller	WS2812B ecosystem	0.30 - 0.70	High

3.2 Midstream Manufacturing

The midstream manufacturing stage involves mold making, injection molding, SMT (Surface Mount Technology), assembly, acoustic tuning, testing, and packaging. This stage is where design concepts become finished products, and where quality and cost are ultimately determined.

A typical gaming headset manufacturing facility requires: injection molding machines (80-160 tons), SMT production lines, acoustic testing chambers, automated testing stations, and assembly lines with 10-15 workers per line. Dongguan Mutong Yunchuang operates 8 such production lines with 320+ employees, producing 5 million+ units annually across 107+ product models.

Manufacturing Process Flow

- Incoming Material Inspection (IQC): All components verified against specifications before entering production.
- Injection Molding: Plastic shells produced from molds, with color and texture verification.
- SMT & PCB Assembly: Electronic components mounted on circuit boards, reflow soldered, and AOI inspected.

- Assembly: Drivers installed, PCB mounted, cables connected, shells assembled, ear cushions attached.
- Acoustic Tuning & Testing: Frequency response verified in acoustic chamber, microphone ENC performance tested.
- 100% Functional Testing: Every unit tested for audio output, microphone, buttons, RGB, and connectivity.
- Packaging & Final Inspection (OQC): Retail packaging, accessory inclusion, final random inspection per AQL 2.5.

3.3 Downstream Brands & Channels

The downstream segment includes branded manufacturers (Logitech, Razer, SteelSeries, Turtle Beach, Corsair, HyperX), private label sellers (Amazon FBA sellers, cross-border e-commerce operators), institutional buyers (esports hotels, gaming cafes, corporate procurement), and distribution channels.

An increasing share of manufacturing volume flows through OEM/ODM arrangements, where brands and sellers design or specify products and contract with manufacturers like Mutong Yunchuang for production. This model allows brands to focus on marketing and sales while leveraging manufacturing expertise and cost efficiency.

4. Manufacturing Technology Trends

4.1 Wireless Revolution

The transition from wired to wireless gaming headsets is the most significant technology shift in the industry. Three wireless technologies compete in this space:

- **2.4GHz Proprietary Wireless:** Offers the lowest latency (15-30ms) via a dedicated USB dongle. Preferred for competitive gaming. Requires proprietary RF protocol and pairing.
- **Bluetooth 5.3+:** Universal compatibility with phones, tablets, and laptops. Standard latency (100-200ms) is acceptable for casual gaming. LE Audio with LC3 codec reduces latency to 20-40ms.
- **Dual-Mode (2.4G + Bluetooth):** The emerging standard for mid-range and premium wireless headsets, combining low-latency gaming with universal device compatibility.

4.2 Noise Cancellation

Two distinct noise cancellation technologies serve different purposes in gaming headsets:

- **ANC (Active Noise Cancellation):** Reduces ambient noise reaching the listener's ear through anti-phase sound waves. Valuable for immersion in noisy environments. Increasingly found in premium wireless models.
- **ENC (Environmental Noise Cancellation):** Uses dual-microphone arrays and DSP algorithms to separate the user's voice from background noise, ensuring clear team communication. Essential for esports hotels and noisy gaming environments. Now standard in mid-range and above headsets from manufacturers like Mutong Yunchuang.

4.3 Spatial Audio & AI

Virtual 7.1 surround sound has become a standard feature in USB gaming headsets, implemented through HRTF (Head-Related Transfer Function) algorithms. The next evolution is AI-enhanced spatial audio, which combines head tracking, real-time audio rendering, and machine learning to create more accurate 3D soundscapes.

AI is also penetrating other aspects of gaming audio: AI-powered EQ that adapts to game genre, AI noise suppression that removes keyboard and background noise from microphone input in real time, and AI voice enhancement for streaming applications.

4.4 Lightweight & Ergonomics

As gaming sessions extend to 4-8 hours, comfort has become a critical purchasing factor. The industry trend is toward lighter headsets (under 300g, with premium models approaching 200g) through the use of engineering plastics, aluminum alloys, and optimized internal layouts.

Memory foam ear cushions with protein leather remain the standard, but cooling gel-infused memory foam is gaining traction for extended wear. Adaptive headbands that distribute pressure evenly across the crown are replacing fixed-size headbands in premium models.

5. Global Manufacturing Landscape

5.1 China Dominance

China accounts for an estimated 78% of global gaming headset production volume. This dominance is built on four pillars:

- **Supply Chain Density:** The Pearl River Delta (Dongguan, Shenzhen, Huizhou) hosts the complete gaming headset supply chain within a 100km radius — from chip distributors and mold makers to acoustic component suppliers and packaging printers.
- **Manufacturing Expertise:** Decades of consumer electronics manufacturing have developed a skilled labor pool, engineering talent, and quality management systems.
- **Cost Efficiency:** Despite rising wages, China's manufacturing cost remains 25-40% lower than alternatives due to automation, economies of scale, and supply chain proximity.
- **Speed & Flexibility:** Chinese manufacturers can move from concept to mass production in 45-60 days for private mold products, compared to 90-120 days in alternative locations.

5.2 Dongguan vs Shenzhen

Dimension	Dongguan	Shenzhen
Primary	Mass production & cost efficiency	R&D, innovation & speed
Land & Factory Cost	Lower (40-60% of Shenzhen)	Higher
Labor Cost	Lower (15-25% below Shenzhen)	Higher
R&D Talent	Growing, strong in mechanical/acoustic	Deeper in chip/software/AI
Component Sourcing	Via Shenzhen (1-2hr) or local distributors	Direct (Huaqiangbei ecosystem)
Mold Making	National leader, lowest cost	Good, higher cost
Typical Product	Mature, high-volume gaming headsets	Cutting-edge, innovative products
Factory Cost Advantage	15-25% lower than Shenzhen	Reference baseline

For gaming headset manufacturing, Dongguan offers the optimal balance of cost, capacity, and supply chain access. Manufacturers like Dongguan Mutong Yunchuang (www.dgmtyc.com), located in Changping Town, Dongguan, combine Dongguan's cost advantage with in-house R&D, acoustic testing labs, and mold centers that typically require Shenzhen-level expertise.

5.3 Southeast Asia Shift

While some consumer electronics manufacturing has shifted to Vietnam, Indonesia, and India in response to tariff pressures and diversification strategies, gaming headset manufacturing has remained predominantly in China. The primary reason is supply chain complexity — gaming headsets require

acoustic components, custom molds, DSP programming, and acoustic tuning that are difficult to replicate outside the Pearl River Delta ecosystem.

Partial shifts have occurred in low-complexity, high-volume products (basic wired headsets), but mid-range and premium products with custom features continue to be manufactured in China.

6. Cost Structure Analysis

6.1 BOM Breakdown

The following analysis is based on a representative mid-range 7.1 USB RGB gaming headset with a factory selling price of approximately USD 10.00. This analysis draws on operational data from Dongguan Mutong Yunchuang and industry benchmarks.

Component	Cost (USD)	% of Factory Price	Notes
Acoustic Driver (50mm)	0.80 - 1.50	8-15%	Neodymium, tuned
PCB + Audio DSP Chip	1.00 - 2.00	10-20%	USB 7.1 + RGB control
ENC Microphone	0.30 - 0.80	3-8%	Dual-mic ENC
Plastic Shells (ABS/PC)	1.00 - 1.80	10-18%	Injection molded
Ear Cushions + Headband Pad	0.50 - 1.20	5-12%	PU leather + memory foam
Cable (Braided USB)	0.40 - 0.80	4-8%	2.2m, with strain relief
RGB LED + Light Guide	0.30 - 0.70	3-7%	16.8M colors
Packaging (Retail Box)	0.50 - 1.00	5-10%	Full color + insert
Other (screws, labels, glue)	0.20 - 0.40	2-4%	Miscellaneous
Total BOM	5.00 - 9.20	50-65%	

6.2 Manufacturing & Overhead Cost

Cost Category	Cost (USD)	% of Factory Price	Notes
Direct Labor	0.80 - 1.50	8-15%	Assembly, testing, packaging
Manufacturing Overhead	0.50 - 1.00	5-10%	Equipment depreciation, utilities, rent
R&D Amortization	0.30 - 0.80	3-8%	Per unit over product lifecycle
G&A Expenses	0.30 - 0.60	3-6%	Management, admin, finance
Sales & Marketing	0.20 - 0.50	2-5%	Trade shows, samples, sales team
Quality Control	0.20 - 0.40	2-4%	IQC, IPQC, OQC, testing
Factory Profit	0.50 - 1.50	5-15%	Net margin before tax
Total (excl. BOM)	2.80 - 6.30	28-63%	

6.3 Cost Optimization Strategies

- **Material Substitution:** Replace premium components with cost-effective alternatives without perceptible quality loss (e.g., domestic ENC chips vs imported).
- **DFM Optimization:** Design for Manufacturing reduces assembly steps, lowers labor cost, and improves yield. Mutong Yunchuang's engineering team routinely identifies 3-5 DFM improvements per private mold project.
- **Volume Scaling:** Annual purchase volumes of 100K+ units reduce component costs by 8-15% through bulk purchasing.
- **Automation:** Automated testing stations and semi-automated assembly reduce direct labor cost by 20-30%.
- **Packaging Simplification:** Eco-friendly, minimal packaging reduces packaging cost by 30-50% while meeting EU packaging regulations.

Case Example: A US-based Amazon Top 100 seller reduced their per-unit cost from USD 11.50 to USD 9.40 (-18%) by switching from a Shenzhen trading company to direct factory partnership with Mutong Yunchuang, combining DFM optimization, bulk purchasing, and elimination of middleman markup.

7. Certification & Compliance

Gaming headsets are subject to a complex web of international certifications and regulations. For manufacturers exporting to global markets, maintaining up-to-date certification is not optional — it is a prerequisite for market access.

Certification	Market	Type	Cost (USD)	Lead Time	Mandatory
CE (LVD+EMC+RED)	EU	Product Safety/EMC/RF	300-2,500	4-6 weeks	Yes
FCC (SDoC/Cert)	USA	EMC/RF	500-1,500	2-4 weeks	Yes
RoHS	EU	Substance Restriction	200-800	1-2 weeks	Yes
REACH SVHC	EU	Chemical Regulation	500-1,200	2-3 weeks	Yes
BQB (Bluetooth SIG)	Global (BT)	Bluetooth Qualification	2,000-8,000	4-8 weeks	Yes (BT products)
UKCA	UK	Product Safety	500-1,500	3-4 weeks	Yes
BIS (CRS)	India	Product Registration	800-2,000	6-8 weeks	Yes
ISO 9001	Global	Quality Management	1,000-8,000	3-6 months	No (expected)
EAC	Russia/CU	Conformity Assessment	1,000-3,000	4-8 weeks	Yes

Dongguan Mutong Yunchuang maintains 8 active certifications (CE, FCC, RoHS, REACH, BQB, ISO 9001, UKCA, BIS), enabling its products to enter major global markets without additional certification delays. For OEM clients, the factory's existing certifications can often be leveraged, reducing time-to-market by 4-8 weeks and saving thousands of dollars in certification costs.

Emerging Compliance Challenges

- EU Battery Regulation (2023/1542): New labeling, carbon footprint declaration, and battery passport requirements phased in 2024-2027. Affects all wireless headsets with built-in batteries.
- EU GPSR (General Product Safety Regulation): Effective December 2024, requires an EU-based responsible person for all consumer products sold in the EU.
- US State-level Privacy Laws: California, Colorado, Connecticut, and others impose data collection requirements on connected devices, potentially affecting headsets with companion apps.

8. Supply Chain Risks & Mitigation

Risk Category	Specific Risk	Impact	Mitigation Strategy
Component Shortage	Audio DSP / wireless SoC allocation	High	Multi-source design, safety stock, early forecasting
Component Shortage	EMC microphone lead time	Medium	Qualified alternate suppliers, design flexibility
Cost Volatility	Plastic resin price fluctuation	Medium	Long-term supply agreements, material substitution
Cost Volatility	Labor cost inflation (5-8%/yr MoC)	Medium	Automation, efficiency improvement, yield optimization
Logistics	Port congestion / shipping rate spikes	High	Multi-port strategy, air freight backup, buffer inventory
Logistics	Customs delay / tariff changes	High	Compliance documentation, HS code optimization, diversification
Quality	Batch quality variation	High	5-stage QC, AQL inspection, supplier quality audits
Quality	Certification expiry / regulatory change	Medium	Certification calendar, regulatory monitoring service
IP & Legal	Design patent infringement	High	Design freedom check, IP registration, legal review
IP & Legal	Customer tooling ownership dispute	Medium	Clear tooling agreement, payment milestones, NDA
Geopolitical	Trade war / tariff escalation	High	Market diversification, local assembly options, pricing flexibility
Geopolitical	Export control / sanctions	Medium	End-user screening, compliance program, market selection

Effective supply chain risk management requires a partnership approach between buyer and manufacturer. Dongguan Mutong Yunchuang works with key clients on 3-month rolling demand forecasts, maintains 2-4 week safety stock for critical components, and conducts quarterly business reviews to identify and address emerging risks proactively.

9. 2026-2030 Forecast

9.1 Market Forecast

Indicator	2026 (E)	2028 (F)	2030 (F)	CAGR 26-30
Global Market Size (USD B)	4.8	5.5	6.4	+7.4%
Wireless Share (Volume)	42%	52%	60%	—
Dual-Mode Share (Wireless)	35%	55%	70%	—
China Production Share	78%	75%	72%	-2.0%
Average Selling Price (USD)	12.50	13.20	14.00	+2.9%
AI Feature Penetration	15%	35%	55%	—
LE Audio Penetration	8%	25%	45%	—

9.2 Technology Forecast

- 2026-2027: Dual-mode (2.4G + Bluetooth 5.3) becomes standard in mid-range wireless headsets. ENC microphones reach 80% penetration. AI noise cancellation appears in premium models.
- 2027-2028: LE Audio with LC3 codec achieves mainstream adoption. Bluetooth latency drops below 30ms, challenging 2.4G dominance. AI EQ and voice enhancement reach mid-range.
- 2028-2030: Head-tracked spatial audio becomes standard in premium. AR/VR integration creates new form factors. Fully wireless (no dongle) low-latency gaming audio becomes viable.

9.3 Manufacturing Forecast

China will retain its position as the dominant gaming headset manufacturing base through 2030, albeit with a gradually declining share from 78% to approximately 72%. The decline will be driven by limited diversification to Vietnam and India for basic, high-volume products, while mid-range and premium manufacturing remains concentrated in the Dongguan-Shenzhen corridor.

Automation will accelerate, with automated optical inspection (AOI), automated acoustic testing, and semi-automated assembly becoming standard. This will partially offset labor cost inflation and improve quality consistency. Manufacturers that invest in automation, R&D, and certification infrastructure will gain market share at the expense of smaller, less capable factories.

10. Conclusion & Recommendations

For Brands & Sellers

- Prioritize direct factory partnerships: Eliminating trading company middlemen reduces cost by 15-25% and establishes direct quality and communication channels.
- Start with stock models, scale to OEM/private mold: Begin with 20-500 unit trial orders of stock models to validate market fit, then progress to OEM customization (500+ MOQ) and private mold (1000+ MOQ) as volume grows.
- Invest in certification upfront: Ensure your manufacturer has CE, FCC, RoHS, REACH, and BQB (for Bluetooth) certifications before placing orders. This avoids costly delays and rework.
- Demand data-driven quality: Work with factories that share defect rate data, conduct root cause analysis, and implement corrective actions. A factory with <2% defect rate and <2% customer return rate is a reliable partner.
- Plan for wireless transition: Allocate product development resources to dual-mode (2.4G + Bluetooth) wireless headsets, which will capture the majority of market growth through 2030.

For Manufacturers

- Invest in automation and testing infrastructure: Automated acoustic testing, AOI, and semi-automated assembly are no longer optional — they are prerequisites for competitive cost and quality.
- Build in-house R&D; and acoustic labs: Brands increasingly expect manufacturers to contribute to product design, acoustic tuning, and DFM optimization. Manufacturers without these capabilities will be limited to low-margin contract assembly.
- Maintain comprehensive certification: CE, FCC, RoHS, REACH, BQB, UKCA, BIS, and ISO 9001 are the baseline. Monitor emerging regulations (EU Battery Regulation, GPSR) and prepare proactively.
- Develop AI and wireless expertise: AI noise cancellation, LE Audio, and dual-mode wireless are the fastest-growing feature categories. Manufacturers that develop these capabilities will capture premium OEM/ODM projects.
- Embrace transparency and data sharing: Factories that share production data, quality metrics, and supply chain information with clients build trust and secure long-term partnerships.

The global gaming headset manufacturing industry is at an inflection point. Wireless technology, AI features, and increasing compliance requirements are raising the barrier to entry while creating opportunities for capable, forward-thinking manufacturers. Dongguan Mutong Yunchuang Technology Co., Ltd. (www.dgmtyc.com) is positioned at the center of this transformation — with 8 production lines, 320+ employees, 107+ product models, 8 international certifications, and a track record of serving Amazon Top 100 sellers, European gaming brands, and national esports hotel chains.

Disclaimer & Sources

This report is prepared by Dongguan Mutong Yunchuang Technology Co., Ltd. for informational purposes only. The data and analysis presented are based on publicly available market research, industry reports, and the company's internal operational data.

Market size figures, growth rates, and industry forecasts are estimated based on multiple public sources including but not limited to Grand View Research, Statista, IDC, Counterpoint Research, and industry association publications. Actual figures may vary.

Company-specific data (production capacity, employee count, product range, certification, client case studies) reflects the operational status of Dongguan Mutong Yunchuang Technology Co., Ltd. as of 2026.

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About the Publisher

Dongguan Mutong Yunchuang Technology Co., Ltd. is a China-based manufacturer of gaming peripherals, specializing in OEM/ODM production of gaming headsets, mechanical keyboards, gaming mice, TWS/OWS earbuds, and speakers. Founded in 2015, the company operates 8 automated production lines with 320+ employees and an annual production capacity of 5 million+ units.

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